

CLAIM AMENDMENTS:

Claim 1 (currently amended): A circuit board ~~for mounting a semiconductor chip, the circuit board including, comprising:~~

a semiconductor chip;

at least one wiring electrically connected to said semiconductor chip;

at least one reinforcement layer for maintaining a strength of the circuit board;

an insulating substrate having a surface, ~~the surface including that is defined by~~ mutually non-overlapping regions, the regions including

a semiconductor chip region, ~~of the surface of the insulating substrate for mounting the semiconductor chip~~ being mounted over said semiconductor chip region, and

at least one wiring region, the wiring being formed on said at least one wiring region, with at least a portion of the wiring being not covered by the semiconductor chip ~~of the surface of the insulating substrate in which wirings electrically connectable to the semiconductor chip are formed on top of the surface, and~~

at least one reinforcement layer region, the reinforcement layer being formed on said at least one reinforcement layer region ~~of the surface of the insulating substrate in which reinforcement layers for maintaining the strength of the circuit board for mounting the semiconductor chip are formed; and~~

a protective film that covers the wirings and the reinforcement layer.

Claims 2-5 (Canceled).

Claim 6 (currently amended): A method of manufacturing a circuit board ~~for mounting a semiconductor chip, comprising:~~

~~providing the circuit board including an insulating substrate having a surface, the surface including mutually non-overlapping regions, the regions including a semiconductor chip region of the surface of the insulating substrate for mounting the semiconductor chip, at least one reinforcement layer region of the surface of the insulating substrate in which reinforcement layers for maintaining the strength of the insulating substrate for mounting the semiconductor chip are formed, and at least one wiring region; of the surface of the insulating substrate in which wirings electrically connected to the semiconductor chip are formed on top of the surface, the method comprising:~~

~~forming a wiring the wirings in the wiring region and adjacent to disposed in a vicinity of the semiconductor chip region;~~

~~forming a the reinforcement layers in the reinforcement layer region and adjacent to disposed in a vicinity of the wiring region; and~~

~~forming a protective film that covers the wirings and the reinforcement layer, and which covers the semiconductor chip region;~~

~~after the protective film is formed, mounting a semiconductor chip on the protective film and over the semiconductor chip region; and~~

~~electrically connecting the wiring to the semiconductor chip.~~

Claims 7-22 (Canceled).

Claim 23 (New): The circuit board for mounting a semiconductor chip of claim 1, wherein none of the wiring is covered by the semiconductor chip.

Claim 24 (New): The circuit board for mounting a semiconductor chip of claim 1, wherein the protective film is disposed under the semiconductor chip and supports the semiconductor chip over the semiconductor chip region, with the semiconductor chip being separated from the wiring and from the surface of the insulating substrate by the protective film.

Claim 25 (New): The circuit board for mounting a semiconductor chip of claim 1, wherein the semiconductor chip has a terminal on an upper surface thereof; further comprising a bonding wire that extends from the terminal to the wiring to electrically connect the semiconductor chip to the wiring.

Claim 26 (new): The circuit board for mounting a semiconductor chip of claim 1, wherein the protective film is disposed under the semiconductor chip, and wherein an upper surface of the protective film is not planar over the wiring and the reinforcement layer, and is planar under the semiconductor chip.

Claim 27 (new): The manufacturing method of claim 6, wherein the mounting of the semiconductor chip includes positioning the semiconductor chip so that at least a portion of the wiring is not covered by the semiconductor chip.

Claim 28 (New): The manufacturing method of claim 27, wherein none of the wiring is covered by the semiconductor chip.

Claim 29 (New): The manufacturing method of claim 6, wherein the electrically connecting the wiring to the semiconductor chip includes extending a bonding wire from a terminal on an upper surface of the semiconductor chip, to the wiring.

Claim 30 (new): The manufacturing method of claim 6, wherein an upper surface of the protective film is not planar over the wiring and the reinforcement layer, and is planar under the semiconductor chip.

Claim 31 (New): A semiconductor device, comprising:

a substrate having an upper surface including a chip mounting region, a wiring region and a reinforcement layer region, the regions being independent from each other, the wiring region being located outside of the chip mounting region, the reinforcement layer region being located outside of the wiring region;
wiring formed in the wiring region;

a reinforcement layer formed in the reinforcement layer region;
a protective film that covers the substrate, the wiring and the reinforcement layer to protect them;
a semiconductor chip arranged over the chip mounting region and on the protective film;
a bonding wire that connects the semiconductor chip to the wiring; and
a sealing resin that seals at least the bonding wire and the semiconductor chip.

Claim 32 (New): The semiconductor device of claim 31, wherein the protective film has a shape corresponding to the surfaces of the wiring, the reinforcement layer and the substrate.

Claim 33 (New): The semiconductor device of claim 31, further comprising solder balls provided on a rear surface of the substrate.

Claim 34 (New): The semiconductor device of claim 33, wherein the solder balls are electrically connected with the wiring.

Claim 35 (New): The semiconductor device of claim 31, wherein the wiring comprises copper.

Claim 36 (New): The semiconductor device of claim 33, wherein the solder balls are provided at positions on the rear surface of the substrate corresponding to the wiring region.

Claim 37 (New): The semiconductor device of claim 31, wherein the protective film is a solder resist.

Claim 38 (New): The semiconductor device of claim 31, wherein a surface of a portion of the protective film positioned in the chip mounting region is planar.